



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Chong Chin Hui, et al.  
Serial No.: 09/982,595  
Filed: 10/18/2001  
For: Die Pad for Integrated Circuits

Docket No.: TI-27874  
Examiner: Parekh, Nitin  
Art Unit: 2811

#6/B  
Am dt  
J. McMillan  
6/28/03

Amendment under 37 CFR 1.111

Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

TECHNOLOGY CENTER  
MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(A)  
I hereby certify that this correspondence is being deposited with  
the U.S. Postal Service as First Class Mail in an envelope addressed  
to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-  
1450 on

6-5-03  
  
Michael K. Skrehot, Reg. No. 36,682

JUN 20 2003  
RECEIVED

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 02/05/03. They are respectfully submitted as a full and complete response to that Action. Applicant hereby petitions for a one month extension of time for the filing of this response. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.